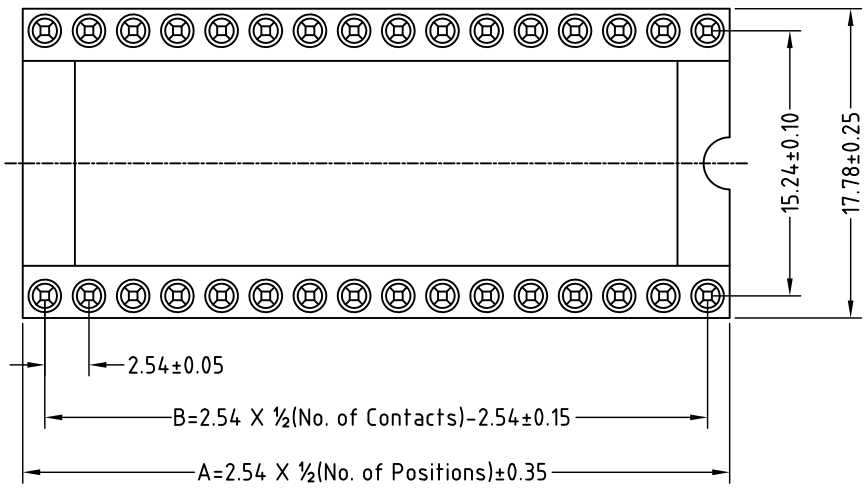

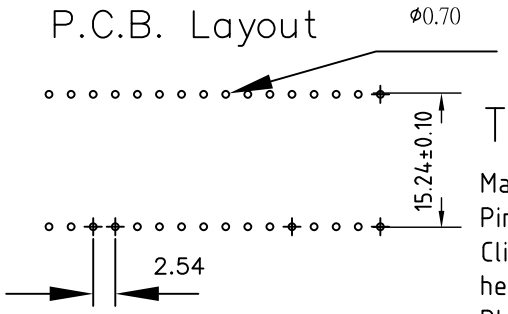

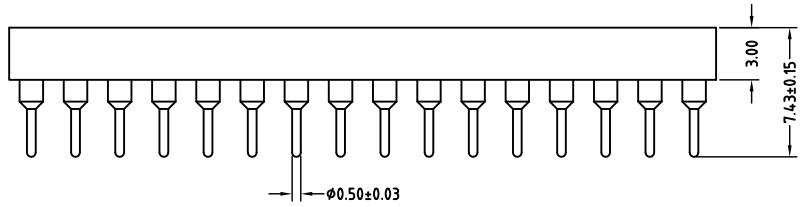

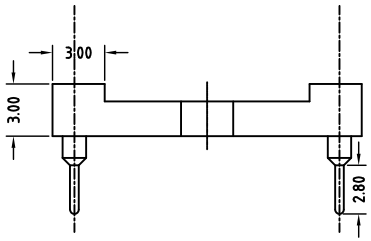

Technical Data

Material:
Pin(outer sleeve): Brass,machined CuZn38Pb2
Clip(contact 4 finger): Beryllium Copper,Phosphor Bronze heat treated
Plating(outer sleeve):
Tin plated:2um/80u" Ni, 5um/200u" Sn
Gold Plated:2um/80u" Ni,Full gold
Plating(contact): 2um/80u" Ni, gold or Tin plated
Insulator(black): Glass filled thermoplastic polyester UL94V-0

Electrical:
Current rating: 3Amps/contact max.
Contact resistance: ≤4mΩ/contact
Insulation resistance: ≥1000MΩ at V=100V
Operaing voltage: 60VAC/DC

Mechanical:
Average insertion force with steel pin of ϕ0.43mm/0.17": <250g
Average withdrawal force with steel pin of ϕ0.43mm/0.17": >50g min.
Mechanical life cycle:min.200
Operaing temperatures: Gold Plsted:-55°C to+105°C
Tin plated:-40°C to+105°C
Soldering temperature: +240°C,10s max.

How To Order

RI－(1)(2)/(3)－(4)/(5)
(1) No. of contact (2) P：Plug S：Socket
(3) 1：Single Row/2：Double Row/3：0.3" Row to Row Pitch/
4：0.4" Row to Row Pitch/6：0.6" Row to Row Pitch
(4) Contact Plating
GF：Gold Flash/T200：Tin 200μ"/SG：Select Gold Flash/
S10：Select Gold plated 10μ"/S15：Select Gold plated 15μ"/S30：Select Gold plated 30μ"
(5) Blanked：Dip Solder Type/W：Wire Wrapping/D：SMD Type
E：Empty，No Bridge
Ex. RI－32S/6－SG/E
Round IC Socket 32Pin，Socket /0.6″ Row to Row Pitch
Select Gold Flash，Empty，No Bar（Dip Solder Type）
Ex. RI－40S/6－SG/E
Round IC Socket 40Pin，Socket /0.6″ Row to Row Pitch
Select Gold Flash，Empty，No Bar（Dip Solder Type）

No. of Positions	DIM"A"	DIM"B"
24	30.48	27.94
28	35.56	33.02
32	40.64	38.10
40	50.80	48.26
48	60.96	58.42

SER	REVISIONS	CHK	DATE
1	新圖發行	Lee	2006-06-02

TOLERANCES ARE
X. ±0.25
X.X ±0.1
X.XX ±0.01
X.XXX ±0.005
X.XXXX ±0.002

FLYiNG

APPROVED	DATE	DRAWTING NO	
CHECKED	DATE	NAME	
DRAWN Lee	DATE 2006/06/02	UNIT MM	SCALE 1:1 / REV A